

Memory-Modul TMS1GB264D081-805xx (Single Side)
Memory-Modul TMS1GB264C081-805xx (Double Side)



Description

These Memory devices are JEDEC standard unbuffered DIMM modules, based on CMOS DDR2 SDRAM technology.

These devices consist of CMOS DDR2 SDRAMs in FBGA packages on a 240-pin glass epoxy substrate. The memory array is designed with Double Data Rate (DDR2) Synchronous DRAMs for unbuffered applications.

The pipelined, multibanked architecture of DDR2 SDRAMs allows for concurrent operation, thereby providing high, effective bandwidth. Decoupling capacitors are mounted on the PCB board in parallel for each DDR2 SDRAM, which provides proper voltage supply impedance over the whole frequency range of operations, in accordance with JEDEC specifications.

These modules feature Serial Presence Detect (SPD) based on a serial EEPROM device, using the 2-pin I2C protocol.

Features

240-pin Unbuffered DDR2 SDRAM
JEDEC standard 1.8V I/O (SSTL_18-compatible)
Auto Refresh (CBR) and Self Refresh Mode
Off-Chip Driver (OCD) Impedance Adjustment
On-Die Termination (ODT) supports termination values of 50, 75, and 150 ohms
Serial Presence Detect (SPD) with EEPROM
Module layout is based on JEDEC standard routing guidelines
Impedance controlled 6-layer PCB Technology
JEDEC standard form factor (133.35 mm x 30.0 mm)
DQS edge-aligned with data for READs
DQS center-aligned with data for WRITEs
Operating Temperature 0°C ~ 75°C
Weight: 18gr (16 IC's) 15gr (8IC's)

Memory-Modul TMS2GB264D081-805xx



Description

These Memory devices are JEDEC standard unbuffered DIMM modules, based on CMOS DDR2 SDRAM technology.

These devices consist of CMOS DDR2 SDRAMs in FBGA packages on a 240-pin glass epoxy substrate. The memory array is designed with Double Data Rate (DDR2) Synchronous DRAMs for unbuffered applications.

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Serial Presence Detect (SPD) with EEPROM
Module layout is based on JEDEC standard routing guidelines
Impedance controlled 6-layer PCB Technology
JEDEC standard form factor (133.35 mm x 30.0 mm)
DQS edge-aligned with data for READs
DQS center-aligned with data for WRITEs
Operating Temperature 0°C ~ 75°C
Weight: 18gr

Technical details

- **2048 MB (2GB) longdim module**
- **128Mx8 IC organisation**
- **x64 module organisation**
- **DDR2-800/PC-6400**
- **Command Rate 400MHz**
- **double sided / 16 ICs**
- **CAS Latency** **5T**
- **RAS to CAS Delay (tRCD)** **5T**
- **RAS Precharge** **5T**

For pin configuration please check www.takems.com/support/index.php

If you have any questions regarding our products you can contact us

Partnumber:	OrderNo	BULK.	Retail
TMS2GB264D081-805		89200	94633

Commodity Code: 84733020

If you have any inquiries, please contact us:

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Web: www.takems.com

09/12

Memory-Modul TMS1GS264D081-805xx (Single Rank)
TMS1GS264C081-805xx (Dual Rank)



Description

These Memory devices are JEDEC standard unbuffered DIMM modules, based on CMOS DDR2 SDRAM technology.

These devices consist of CMOS DDR2 SDRAMs in FBGA packages on a 240-pin glass epoxy substrate. The memory array is designed with Double Data Rate (DDR2) Synchronous DRAMs for unbuffered applications.

The pipelined, multibanked architecture of DDR2 SDRAMs allows for concurrent operation, thereby providing high, effective bandwidth. Decoupling capacitors are mounted on the PCB board in parallel for each DDR2 SDRAM, which provides proper voltage supply impedance over the whole frequency range of operations, in accordance with JEDEC specifications.

These modules feature Serial Presence Detect (SPD) based on a serial EEPROM device, using the 2-pin I2C protocol.

Features

200-pin Unbuffered DDR2 SDRAM
JEDEC standard 1.8V I/O (SSTL_18-compatible)
Auto Refresh (CBR) and Self Refresh Mode
Off-Chip Driver (OCD) Impedance Adjustment
On-Die Termination (ODT) supports termination values of 50, 75, and 150 ohms
Serial Presence Detect (SPD) with EEPROM
Module layout is based on JEDEC standard routing guidelines
Impedance controlled 6-layer PCB Technology
JEDEC standard form factor (68 mm x 30.0 mm)
DQS edge-aligned with data for READs
DQS center-aligned with data for WRITEs
Operating Temperature 0°C ~ 75°C
Weight: 8gr
Warranty: 10 Years

Technical details

- **1024 MB (1GB) SO-dimm module**
- **128Mx8 IC organisation (Single Rank Module)**
- **64Mx8 IC organisation (Dual Rank Module)**
- **x64 module organisation**
- **DDR2-800/PC-6400**
- **Command Rate 400MHz**
- **TMS1GS264D081-805 / 8 ICs**
- **TMS1GS264C081-805 / 16 IC's**
- **CAS Latency 5T**
- **RAS to CAS Delay (tRCD) 5T**
- **RAS Precharge 5T**

Partnumber:	OrderNo	BULK.	Retail
TMS1GS264C081-805		on request	on request
TMS1GS264D081-805		89164	94645

Commodity Code: 84733020

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Memory-Modul TMS2GS264D081-805xx



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- **2048 MB (2GB) SO-dimm module**
- **128Mx8 IC organisation**
- **x64 module organisation**
- **DDR2-800/PC-6400**
- **Command Rate 400MHz**
- **double sided / 16 ICs**
- **CAS Latency** **5T**
- **RAS to CAS Delay (tRCD)** **5T**
- **RAS Precharge** **5T**

Partnumber:	OrderNo	BULK.	Retail
TMS2GS264D081-805		89220	94645

Commodity Code: 84733020

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